2SC5863

Silicon NPN epitaxial planar type

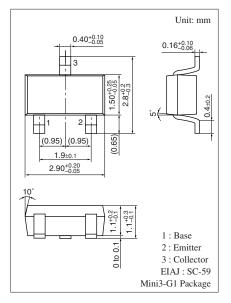
For general amplification

■ Features

- ullet High collector-emitter voltage (Base open) V_{CEO}
- High transition frequency f_T

■ Absolute Maximum Ratings $T_a = 25$ °C

Parameter	Symbol	Rating	Unit	
Collector-base voltage (Emitter open)	V _{CBO}	300	V	
Collector-emitter voltage (Base open)	V _{CEO}	300	V	
Emitter-base voltage (Collector open)	V_{EBO}	7	V	
Collector current	I_C	70	mA	
Peak collector current	I_{CP}	100	mA	
Collector power dissipation	P_{C}	200	mW	
Junction temperature	T_{j}	150	°C	
Storage temperature	T _{stg}	-55 to +150	°C	



Marking Symbol: 7H

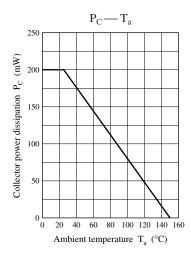
■ Electrical Characteristics $T_a = 25$ °C ± 3 °C

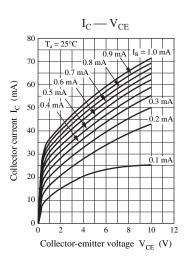
Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Collector-emitter voltage (Base open)	V _{CEO}	$I_C = 100 \ \mu A, I_B = 0$	300			V
Emitter-base voltage (Collector open)	V_{EBO}	$I_E = 1 \mu A, I_C = 0$	7			V
Collector-emitter cutoff current (Base open)	I_{CEO}	$V_{CE} = 120 \text{ V}, I_B = 0$			1	μΑ
Forward current transfer ratio *	h _{FE}	$V_{CE} = 10 \text{ V}, I_{C} = 5 \text{ mA}$	60		220	
Collector-emitter saturation voltage	V _{CE(sat)}	$I_C = 50 \text{ mA}, I_B = 5 \text{ mA}$			1.2	V
Collector output capacitance	C _{ob}	$V_{CB} = 10 \text{ V}, I_E = 0, f = 1 \text{ MHz}$			10	pF
(Common base, input open circuited)						
Transition frequency	f_T	$V_{CB} = 10 \text{ V}, I_E = -10 \text{ mA}, f = 200 \text{ MHz}$	50	80		MHz

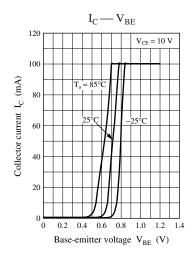
Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 measuring methods for transistors.

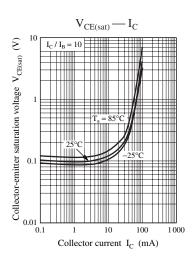
2. *: Rank classification

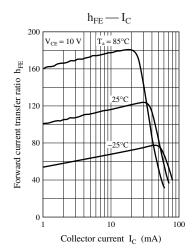
Rank	Q	R
h_{FE}	60 to 150	100 to 220

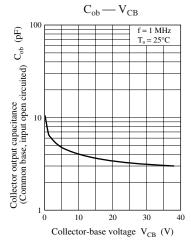












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